

U.S. 09/831,460  
Atty. Docket No.: N17 732

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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KWD  
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In re Patent Application of:

D. De Leeuw, et al.

Group Art Unit: 1773

Serial No.: 09/831,460

Examiner: R. Zacharia

Filed: May 8, 2001

For: Electronic Component Comprising an Electrically Conductive Relief Structure and  
Method of Manufacturing a Relief Structure on a Substrate

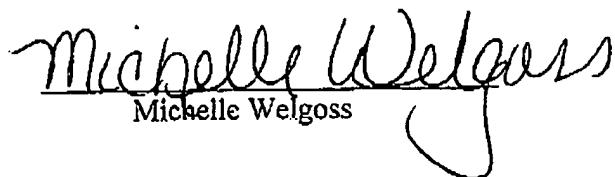
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Honorable Assistant Commissioner of Patents  
Washington, D.C. 20231

Date: November 27, 2002

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I hereby certify that this Amendment and/or RESPONSE under 37 C.F.R. § 1.111  
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Michelle Welgoss

AMENDMENT and/or RESPONSE under 37 C.F.R. § 1.111

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Sir:

In response to the Office Action dated August 27, 2002, the following  
amendments and remarks are made in connection with the above application.